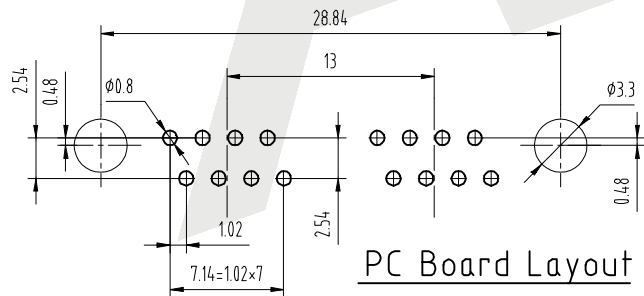
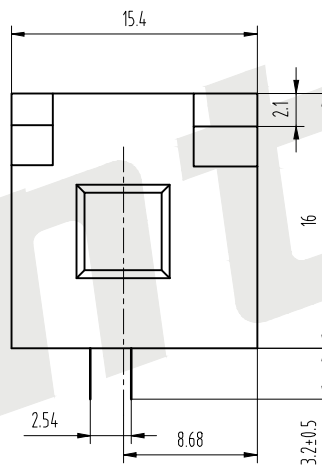
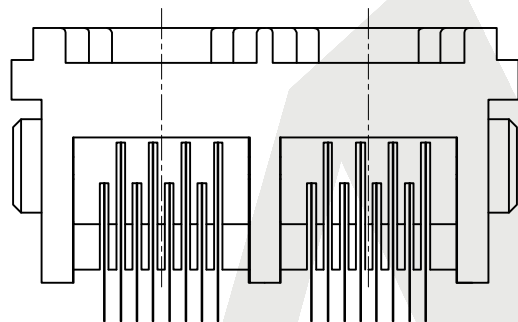
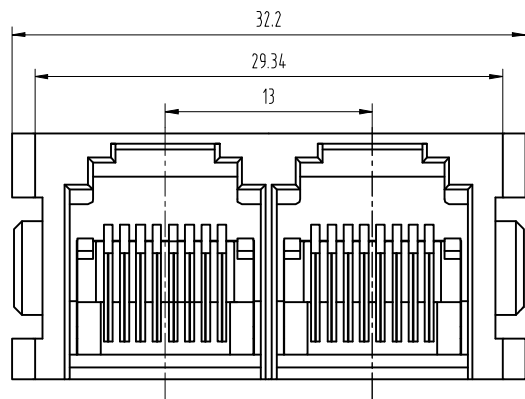


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1μ~50μ"OVER NICKEL IN CONTACT AREA. 150μ" TIN PLATIN.OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTTON PRB-SOLDER :1 LB MIN

REVRONMENTAL

- 1. STORAGE : -40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5224 - 8P - 8C - X - A - B

① ② ③ ④ ⑤ ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact PIating
G0:G0ld flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
- ⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
- ⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

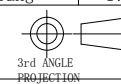
Antenk® ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 17/08/2019
CHECK BobYang DATE 17/08/2019

TITLE: RJ11 Top entry 8P8C 1X2P, Full plastic

DRAWING NO: ATRJ5224-8P8C-X-A-B

PRODUCT NO: ATRJ5224-8P8C-X-A-B



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		